

Figure 2:

AN: PAT 1993-330914
TI: Mfr. of gold-based solder material, useful for semiconductor device prodn. by heat treating amorphous or polycrystalline gold-based eutectic alloy foil by quench solidification at temp. lower than m.pt. of alloy
PN: JP05237694-A
PD: 17.09.1993
AB: Solder material mfr. comprises heat treating an amorphous or polycrystalline Au-based eutectic alloy foil obtd. by quench-solidification under an inert atmos. at a temp. not lower than the temp. at which the intermetallic cpds. generated inside the foil may disappear but at a temp. not higher than the m.pt. of the Au based eutectic alloy. Also claimed is the mfr. by heat treating an amorphous or polycrystalline Au-Si based eutectic alloy foil produced by quench-solidification under an inert atmos. in the temp. range of 200-363 deg.C. Pref. the process is applicable to Au alloys such as Au-Si based, Au-Sn based, Au-Ge based, Au-Sb based and Au-Ga based alloys, but pref. provides an Au-3.15 wt.% Si alloy.; For assembling semiconductor elements to provide a device and for connecting semiconductor components. The foil can be mechanically processed.
PA: (YAWA) NIPPON STEEL CORP;
FA: JP05237694-A 17.09.1993;
CO: JP;
IC: B23K-035/40;
MC: L03-A01B6; M23-A01; U11-A08B; U11-D03B3; X24-A01A;
DC: L03; M23; P55; U11; X24;
FN: 1993330914.gif
PR: JP0323149 06.12.1991;
FP: 17.09.1993
UP: 11.10.1993

